MOSFET – Power, Single, N-Channel, μ Cool, UDFN6, 1.6x1.6x0.55 mm 30 V, 13 m Ω , 8.2 A

Features

- UDFN Package with Exposed Drain Pads for Excellent Thermal Conduction
- Low Profile UDFN 1.6 x 1.6 x 0.55 mm for Board Space Saving
- Ultra Low R_{DS(on)}
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Power Load Switch
- Wireless Charging
- DC-DC Converters
- Motor Drive

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	30	V
Gate-to-Source Volta	age		V _{GS}	±20	V
Continuous Drain		T _A = 25°C	I _D	8.2	Α
Current R _{0JA} (Note 1, 3)	Steady	T _A = 85°C		5.9	
Power Dissipation R _{0JA} (Note 1, 3)	State	T _A = 25°C	P _D	1.52	W
Continuous Drain		T _A = 25°C	I _D	5.3	Α
Current R _{0JA} (Note 2, 3)	Steady	T _A = 85°C		3.8	
Power Dissipation R _{0JA} (Note 2, 3)	State	T _A = 25°C	P _D	0.65	W
Pulsed Drain Current $t_p = 10 \mu s$		I _{DM}	24	Α	
Operating Junction and Storage Temperature			T_J , T_{STG}	-55 to 150	°C
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 1, 3)	$R_{ heta JA}$	82.5	°C/W
Junction-to-Ambient – Steady State min Pad (Note 2, 3)	$R_{\theta JA}$	194.8	O/VV

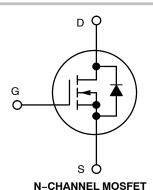
^{1.} Surface-mounted on FR4 board using 1 in² pad size, 2 oz Cu pad.



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MOSFET					
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX			
30 V	13 mΩ @ 10 V	8.2 A			
	18 mΩ @ 4.5 V	J.2.A			



MARKING DIAGRAM



UDFN6 (μCOOL) CASE 517AU



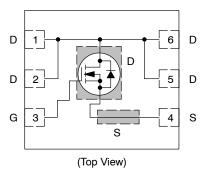
AL = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

PIN CONNECTIONS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

- Surface-mounted on FR4 board using the min pad size, 2 oz Cu pad.
 The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
 This device does not have ESD protection diode.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Units
OFF CHARACTERISTICS		•		•			•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V,	I _D = 250 μA	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 250 μA, ref to 25°C			13.4		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 24 V	$T_{J} = 25^{\circ}C$ $T_{.J} = 125^{\circ}C$			1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V,	V _{GS} = 20 V			100	nA
ON CHARACTERISTICS (Note 5)	400	B0 /					
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, I _D = 250 μA	1.2		2.2	V
Negative Threshold Temp. Coefficient	V _{GS(TH)} /T _J	ac 20	A, ref to 25°C		-4.2		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}		V, I _D = 8.0 A		10	13	mΩ
	,	V _{GS} = 4.5	V, I _D = 8 A		14	18	
Forward Transconductance	9FS	V _{DS} = 1.5	V, I _D = 8 A		24		S
CHARGES & CAPACITANCES							
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1 \text{ MHz,}$ $V_{DS} = 15 \text{ V}$			620		pF
Output Capacitance	C _{OSS}				280		1
Reverse Transfer Capacitance	C _{RSS}				15		
Total Gate Charge	Q _{G(TOT)}				5		nC
Threshold Gate Charge	Q _{G(TH)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 15 \text{ V};$ $I_D = 8 \text{ A}$			0.8		
Gate-to-Source Charge	Q _{GS}				1.8		
Gate-to-Drain Charge	Q_{GD}				1.6		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 15 V; I _D = 8 A			11		nC
SWITCHING CHARACTERISTICS, VG	S = 4.5 V (Note 6)						
Turn-On Delay Time	t _{d(ON)}				9		ns
Rise Time	t _r	V _{GS} = 4.5 V	, V _{DD} = 15 V,		26		
Turn-Off Delay Time	t _{d(OFF)}	I _D = 8 A,	$R_{\rm QDD} = 15 \text{ V},$ $R_{\rm G} = 6 \Omega$		13]
Fall Time	t _f	1			3		
SWITCHING CHARACTERISTICS, VG	S = 10 V (Note 6)						
Turn-On Delay Time	t _{d(ON)}				6		ns
Rise Time	t _r	V_{GS} = 10 V, V_{DD} = 15 V, I_{D} = 8 A, R_{G} = 6 Ω			24		
Turn-Off Delay Time	t _{d(OFF)}				16		
Fall Time	t _f				2.3		
DRAIN-SOURCE DIODE CHARACTER	RISTICS						
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	T _J = 25°C		8.0	1	V
		I _S = 8 A T _J = 125°C		0.7			

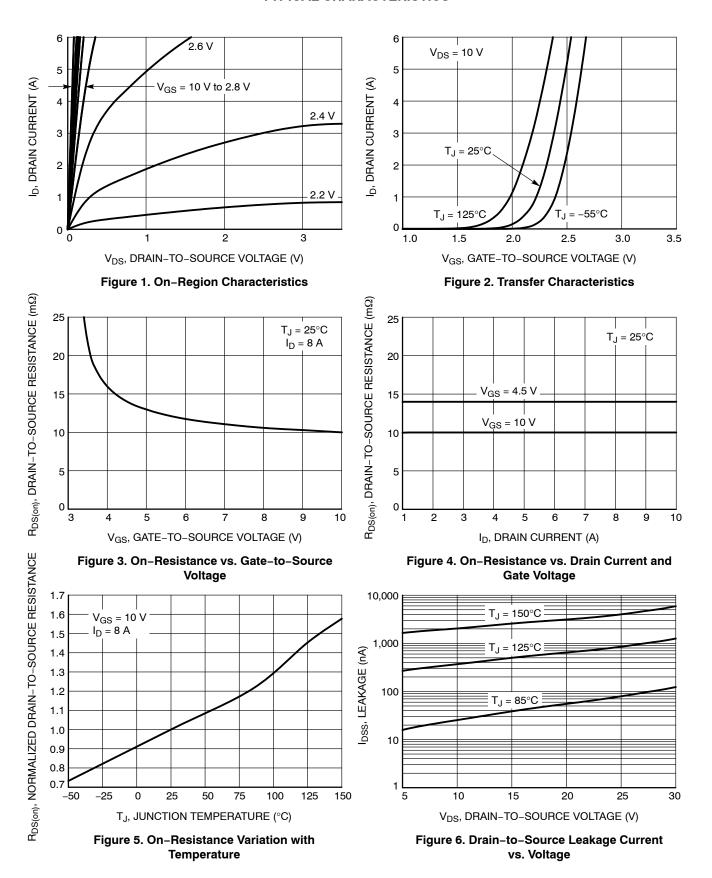
- 5. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 6. Switching characteristics are independent of operating junction temperatures.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

		, ,				
Parameter	Symbol	Test Condition	Min	Тур	Max	Units
DRAIN-SOURCE DIODE CHARACTER	RISTICS					
Reverse Recovery Time	t _{RR}			23		ns
Charge Time	t _a	V _{GS} = 0 V, dls/dt = 100 A/μs,		12		
Discharge Time	t _b	V_{GS} = 0 V, dls/dt = 100 A/ μ s, I_S = 8 A		11		
Reverse Recovery Charge	Q _{RR}			10		nC

^{5.} Pulse Test: pulse width \leq 300 μ s, duty cycle \leq 2%.
6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

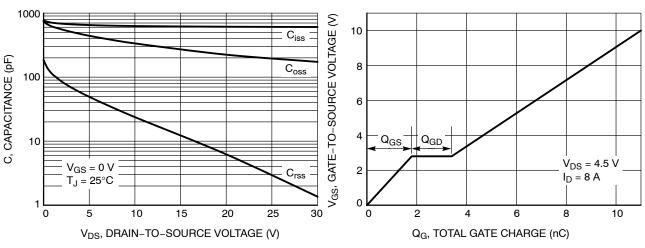


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source vs. Total Charge

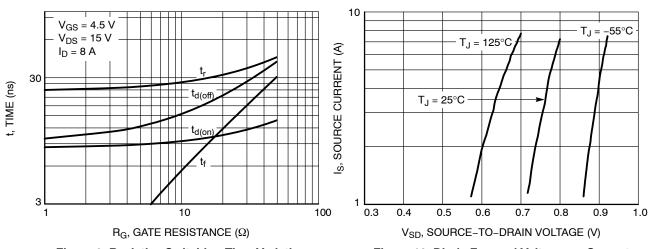


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

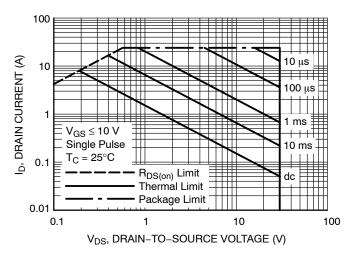


Figure 11. Maximum Rated Forward Biased Safe Operating Area

TYPICAL CHARACTERISTICS

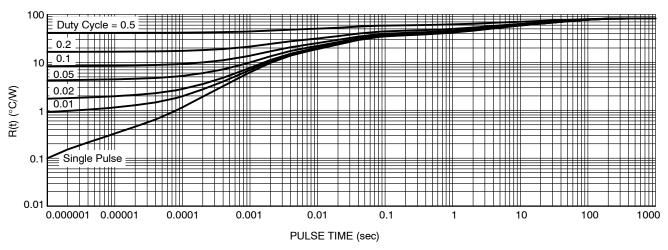


Figure 12. Thermal Response

DEVICE ORDERING INFORMATION

Device	Package	Shipping [†]
NTLUS020N03CTAG	UDFN6 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





UDFN6 1.6x1.6, 0.5P CASE 517AU ISSUE O

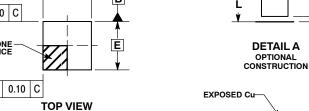
DATE 16 OCT 2008

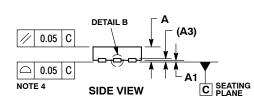
NOTES

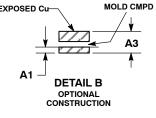
- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.

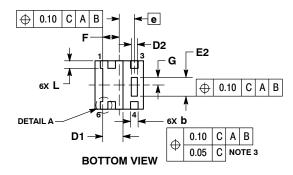
	MILLIMETERS			
DIM	MIN	MAX		
Α	0.45	0.55		
A 1	0.00	0.05		
A3	0.13	REF		
b	0.20	0.30		
D	1.60 BSC			
Е	1.60 BSC			
е	0.50 BSC			
D1	0.62 0.72			
D2	0.15	0.25		
E2	0.57	0.67		
F	0.55 BSC			
G	0.25 BSC			
L	0.20	0.30		
L1		0.15		

·D В 0.10 C PIN ONE REFERENCE









GENERIC MARKING DIAGRAM*



XX = Specific Device Code

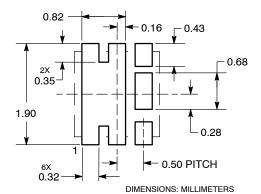
M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either loca-

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

SOLDERMASK DEFINED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN6 1.6x1.6, 0.5P		PAGE 1 OF 1	

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